# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



March 2006



# FFA30UP20DN Ultrafast Recovery Power Rectifier

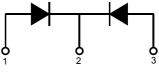
### Features

- Ultrafast with Soft Recovery : < 45ns (@I<sub>F</sub> = 15A)
- High Reverse Voltage : V<sub>RRM</sub> = 200V
- Avalanche Energy Rated
- Planar Construction

# Applications

- Output Rectifiers
- Switching Mode Power Supply
- Free-wheeling diode for motor application
- Power switching circuits





1. Anode 2. Cathode 3. Anode

1.Anode 2.Cathode 3.Anode

Absolute Maximum Ratings (per diode) T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	200	V	
V <sub>RWM</sub>	Working Peak Reverse Voltage	200	V	
V <sub>R</sub>	DC Blocking Voltage	200	V	
I <sub>F(AV)</sub>	Average Rectified Forward Current @ $T_{C} = 120^{\circ}C$	15	A	
I <sub>FSM</sub>	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	150	A	
$T_{J,}T_{STG}$	Operating Junction and Storage Temperature	- 65 to +150	°C	

# **Thermal Characteristics**

Symbol	Parameter	Мах	Units
$R_{ ext{ heta}JC}$	Maximum Thermal Resistance, Junction to Case	2.3	°C/W

# Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
F30UP20DN	FFA30UP20DNTU	TO-3PN	-	-	30

Symbol	Parameter		Min.	Тур.	Max.	Units
V <sub>FM</sub> *	I <sub>F</sub> = 15A I <sub>F</sub> = 15A	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C	-	-	1.15 1.0	V V
I <sub>RM</sub> *	V <sub>R</sub> = 200V V <sub>R</sub> = 200V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C	-	- -	100 500	μΑ μΑ
t <sub>rr</sub>	$I_F$ =1A, di/dt = 100A/µs, V <sub>CC</sub> = 30V $I_F$ =15A, di/dt = 200A/µs, V <sub>CC</sub> = 130V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 25 °C	-	- -	35 45	ns ns
t <sub>a</sub> t <sub>b</sub> Q <sub>rr</sub>	I <sub>F</sub> =15A, di/dt = 200A/μs, V <sub>CC</sub> = 130V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 25 °C T <sub>C</sub> = 25 °C T <sub>C</sub> = 25 °C	- - -	13 11 24	- - -	ns ns nC
W <sub>AVL</sub>	Avalanche Energy (L = 40mH)		20	-	-	mJ

#### Electrical Characteristics (per diode) T<sub>C</sub> = 25°C unless otherwise noted

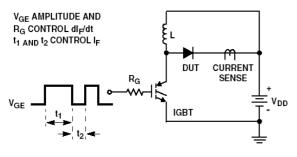
\* Pulse Test: Pulse Width=300 $\mu s,$  Duty Cycle=2%

$$\begin{split} &I_{MAX} = 1A \\ &L = 40mH \\ &R < 0.1\Omega \\ &E_{AVL} = 1/2LI^2 \left[ V_{R(AVL)} / (V_{R(AVL)} - V_{DD}) \right] \\ &Q_1 = IGBT (BV_{CES} > DUT V_{R(AVL)}) \end{split}$$

Л۰

Q1

### **Test Circuit and Waveforms**



trr TEST CIRCUIT

L R

+٩

 $V_{DD}$ 

V<sub>DD</sub>

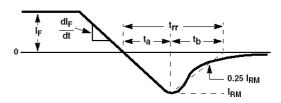
ຼີ

CURRENT

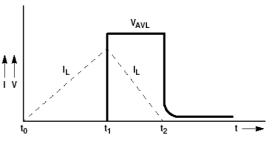
SENSE

DUT

AVALANCHE ENERGY TEST CIRCUIT



trr WAVEFORMS AND DEFINITIONS



AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

### **Typical Performance Characteristics** Figure 1. Typical Forward Voltage Drop 100 FORWARD CURRENT, IF[A] 10 T\_ = 75°C 25°C T<sub>c</sub> = 125°C 0.1 ∟ 0.2 0.4 0.8 1.0 1.2 1.4 1.6 FORWARD VOLTAGE, V<sub>F</sub>[V]



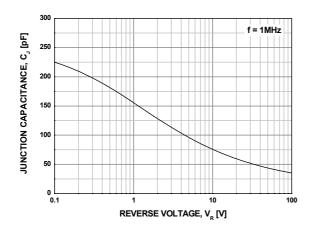


Figure 5. Typical Reverse Recovery Current

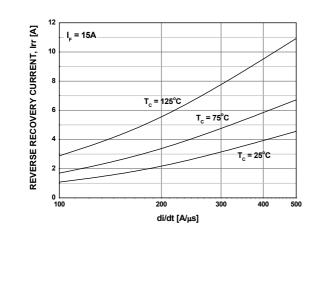


Figure 2. Typical Reverse Current

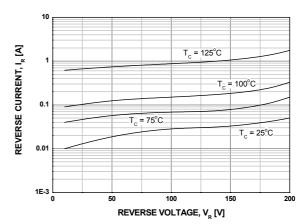


Figure 4. Typical Reverse Recovery Time

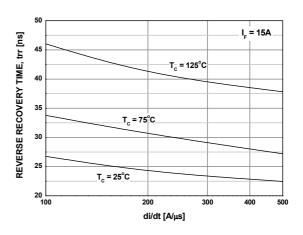
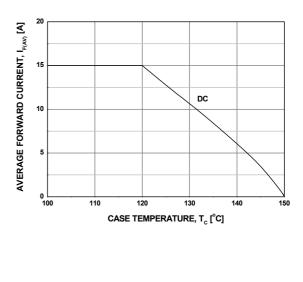
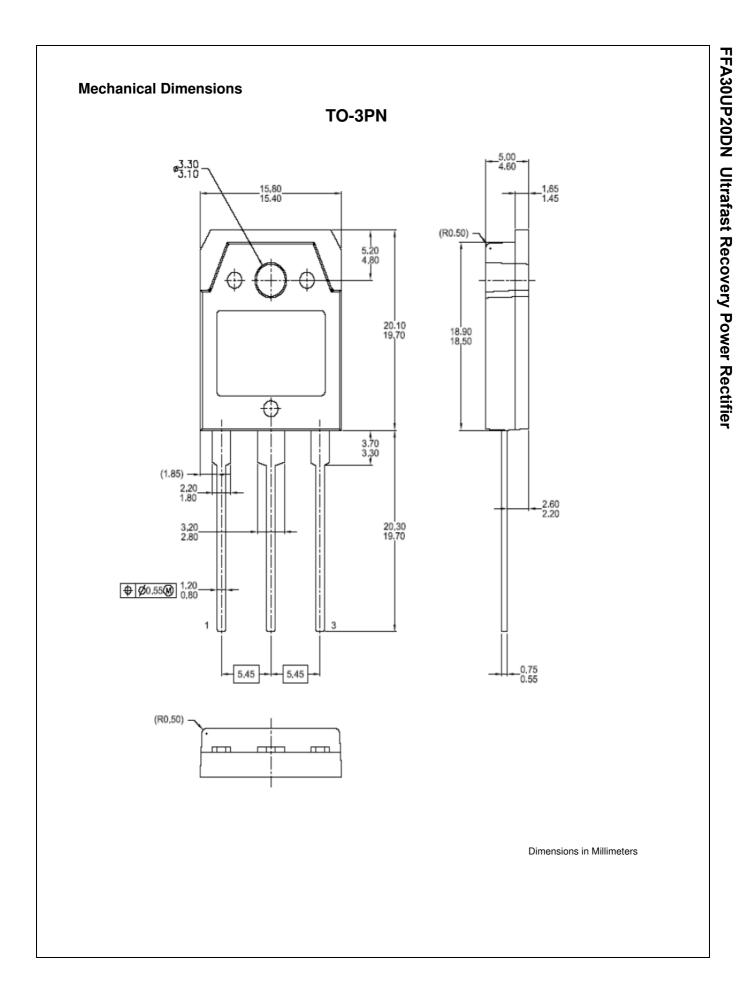


Figure 6. Forward Current Deration Curve





#### TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FAST <sup>®</sup>
ActiveArray™	FASTr™
Bottomless™	FPS™
Build it Now™	FRFET™
CoolFET™	GlobalOptois
CROSSVOLT™	GTO™
DOME™	HiSeC™
EcoSPARK™	l <sup>2</sup> C™
E <sup>2</sup> CMOS™	i-Lo™
EnSigna™	ImpliedDisco
FACT™	IntelliMAX™
FACT Quiet Series	ГМ
Across the board. A	round the world.™

IST<sup>®</sup> IST<sup>™</sup> ST<sup>™</sup> ST<sup>™</sup> SET<sup>™</sup> DalOptoisolator<sup>™</sup> O<sup>™</sup> SeC<sup>™</sup> C<sup>™</sup> pliedDisconnect<sup>™</sup> elliMAX<sup>™</sup> e world.<sup>™</sup>

**ISOPLANAR™** LittleFET™ MICROCOUPLER™ MicroFET™ MicroPak™ **MICROWIRE™** MSX™ MSXPro™ OCX™ OCXPro™ **OPTOLOGIC**<sup>®</sup> **OPTOPLANAR™** PACMAN™ POP™ Power247™ PowerEdge™

PowerSaver™ PowerTrench® **QFET<sup>®</sup>** QS™ QT Optoelectronics™ Quiet Series™ RapidConfigure™ RapidConnect™ μSerDes™ Scalar Pump™ SILENT SWITCHER<sup>®</sup> SMART START™ SPM™ Stealth™ SuperFET™ SuperSOT™-3

SuperSOT<sup>™</sup>-6 SuperSOT<sup>™</sup>-8 SyncFET<sup>™</sup> TCM<sup>™</sup> TinyLogic<sup>®</sup> TINYOPTO<sup>™</sup> TruTranslation<sup>™</sup> UHC<sup>™</sup> UltraFET<sup>®</sup> UniFET<sup>™</sup> VCX<sup>™</sup> Wire<sup>™</sup>

#### DISCLAIMER

The Power Franchise<sup>®</sup>

Programmable Active Droop™

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user. 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### **PRODUCT STATUS DEFINITIONS**

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete Not In Production		This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

Rev. 118